

300mA, Low Power Consumption, High Voltage CMOS LDO Regulator

1 FEATURES

- **Low Quiescent Current I_Q : 3 μ A (TYP)**
- **300mA Nominal Output Current**
- **Low Dropout Voltage**
- **Low Temperature Coefficient**
- **High Input Voltage (up to 45V)**
- **Output Voltage Accuracy: $\pm 1\%$ / $\pm 2\%$**
- **Fixed Output Voltage: 1.8V, 2.5V, 3.0V, 3.3V and 5.0V**
- **Current Limit Protection**
- **Over Temperature Protection**
- **SOT23-3, SOT23-5, SOT89-3L and SOT223 and SOP8 Packages**

2 APPLICATIONS

- **Smart Power Network Equipment**
- **Portable Power Tools**
- **BMS systems**
- **Motor control system/Industrial control system**
- **Power Meter/Instrument**
- **White Goods**
- **Vehicle-mounted system**
- **Battery-Powered Equipment**
- **Automotive Head Unit**
- **Security Equipment**
- **Communication Equipment**

3 DESCRIPTIONS

The RS3007 series is a set of Low power high voltage regulators implemented in CMOS technology. Which can provide 300mA output current. The device allows input voltage as high as 45V. It is very suitable for multi-cell battery systems, bus voltage power supply systems and other high DC voltage systems. Wide input voltage can make it well withstand the impact of surge voltage and ensure the stability of output voltage.

The RS3007 series only consume 3 μ A (typical), Which is particularly important in battery power system, can reduce the standby power consumption of the whole system.

The RS3007 is available in Green SOT23-3, SOT23-5, SOT89-3L and SOT223 and SOP8 packages, for the different application's requirements.

Device Information ⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
RS3007	SOT23-3(3)	1.60mm×2.92mm
	SOT23-5(5)	1.60mm×2.92mm
	SOT89-3L(3)	2.45mm×4.50mm
	SOT223(3)	3.50mm×7.00mm
	SOP8(8)	4.90mm×3.90mm

(1) For all available packages, see the orderable addendum at the next page of the data sheet.

4 Typical Application Schematic

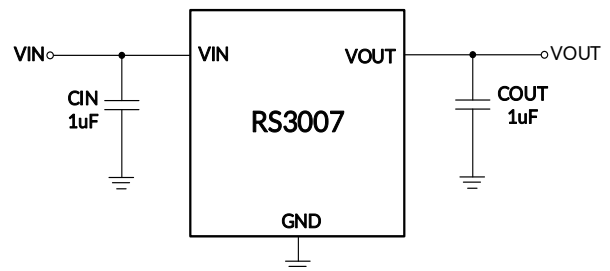


Table of Contents

1 FEATURES	1
2 APPLICATIONS	1
3 DESCRIPTIONS	1
4 Typical Application Schematic	1
5 Revision History	3
6 PACKAGE/ORDERING INFORMATION ⁽¹⁾	4
7 Pin Configuration and Functions (Top View)	6
8 Specifications	8
8.1 Absolute Maximum Ratings	8
8.2 ESD Ratings	8
8.3 Recommended Operating Conditions	8
8.4 Thermal Information	9
8.5 ELECTRICAL CHARACTERISTICS	10
8.6 TYPICAL CHARACTERISTICS	11
9 DETAILED DESCRIPTION	13
9.1 Overview	13
9.2 Functional Block Diagram	13
9.3 Thermal Considerations	13
9.4 Applications Note:	13
10 PACKAGE OUTLINE DIMENSIONS	14
11 TAPE AND REEL INFORMATION	19

5 Revision History

Note: Page numbers for previous revisions may differ from page numbers in the current version.

VERSION	Change Date	Change Item
A.1	2020/03/16	Initial version completed
A.2	2020/06/03	1) Added part-number to ordering information table 2) Added SOT223(L Type) package
A.3	2020/09/11	1) Added part-number to ordering information table 2) Added SOT223 and SOP8 package 3) Added 3.0 and 5.0 V _{OUT} Accuracy of 1%
A.4	2023/05/29	1) Change SOT23-5, SOT23-3 and SOT89-3L (L-Type) Thermal Information on Page 6 @A.3 Version. 2) Added the TAPE AND REEL INFORMATION 3) Update RS3007-2.5YE3 PACKAGE OPTION on Page 5 @A.3 Version. 4) Delete RS3007-3.3AYD3 ORDERING NUMBER on Page 5 @A.3 Version.
A.5	2023/09/04	Update SOP-8 PACKAGE MARKING on Page 5 @A.4 Version

6 PACKAGE/ORDERING INFORMATION (1)

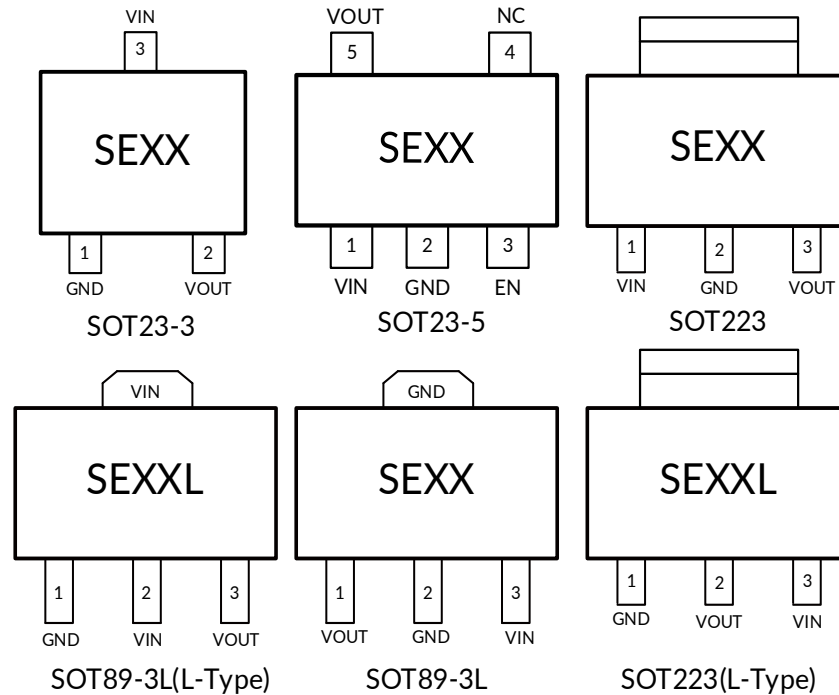
PRODUCT	ORDERING NUMBER	V _{OUT} (V)	V _{OUT} Accuracy	PACKAGE LEAD	PACKAGE MARKING ⁽²⁾	PACKAGE OPTION
RS3007-1.8	RS3007-1.8YF3	1.8	±2%	SOT23-3	SE18	Tape and Reel,3000
	RS3007-1.8SYF5	1.8	±2%	SOT23-5	SE18	Tape and Reel,3000
	RS3007-1.8YE3L	1.8	±2%	SOT89-3L L-Type	SE18L	Tape and Reel,1000
	RS3007-1.8YE3	1.8	±2%	SOT89-3L	SE18	Tape and Reel,1000
RS3007-2.5	RS3007-2.5YF3	2.5	±2%	SOT23-3	SE25	Tape and Reel,3000
	RS3007-2.5SYF5	2.5	±2%	SOT23-5	SE25	Tape and Reel,3000
	RS3007-2.5YE3L	2.5	±2%	SOT89-3L L-Type	SE25L	Tape and Reel,1000
	RS3007-2.5YE3	2.5	±2%	SOT89-3L	SE25	Tape and Reel,1000
RS3007-3.0	RS3007-3.0YF3	3.0	±2%	SOT23-3	SE30	Tape and Reel,3000
	RS3007-3.0SYF5	3.0	±2%	SOT23-5	SE30	Tape and Reel,3000
	RS3007-3.0YE3L	3.0	±2%	SOT89-3L L-Type	SE30L	Tape and Reel,1000
	RS3007-3.0YE3	3.0	±2%	SOT89-3L	SE30	Tape and Reel,1000
	RS3007-3.0YD3	3.0	±2%	SOT223	SE30	Tape and Reel,2500
	RS3007-3.0YD3L	3.0	±2%	SOT223 L-Type	SE30L	Tape and Reel,2500
RS3007-3.3	RS3007-3.3YF3	3.3	±2%	SOT23-3	SE33	Tape and Reel,3000
	RS3007-3.3SYF5	3.3	±2%	SOT23-5	SE33	Tape and Reel,3000
	RS3007-3.3YE3L	3.3	±2%	SOT89-3L L-Type	SE33L	Tape and Reel,1000
	RS3007-3.3YE3	3.3	±2%	SOT89-3L	SE33	Tape and Reel,1000
	RS3007-3.3YD3	3.3	±2%	SOT223	SE33	Tape and Reel,2500
	RS3007-3.3YD3L	3.3	±2%	SOT223 L-Type	SE33L	Tape and Reel,2500
RS3007-5.0	RS3007-5.0YF3	5.0	±2%	SOT23-3	SE50	Tape and Reel,3000
	RS3007-5.0SYF5	5.0	±2%	SOT23-5	SE50	Tape and Reel,3000
	RS3007-5.0YE3L	5.0	±2%	SOT89-3L L-Type	SE50L	Tape and Reel,1000
	RS3007-5.0YE3	5.0	±2%	SOT89-3L	SE50	Tape and Reel,1000
	RS3007-5.0YD3	5.0	±2%	SOT223	SE50	Tape and Reel,2500
	RS3007-5.0YD3L	5.0	±2%	SOT223 L-Type	SE50L	Tape and Reel,2500

PRODUCT	ORDERING NUMBER	V _{out} (V)	V _{out} Accuracy	PACKAGE LEAD	PACKAGE MARKING ⁽²⁾	PACKAGE OPTION
RS3007-3.0	RS3007-3.0AYF3	3.0	±1%	SOT23-3	SE30	Tape and Reel,3000
	RS3007-3.0ASYF5	3.0	±1%	SOT23-5	SE30	Tape and Reel,3000
	RS3007-3.0AYK	3.0	±1%	SOP-8	SE30	Tape and Reel,4000
RS3007-3.3	RS3007-3.3AYF3	3.3	±1%	SOT23-3	SE33	Tape and Reel,3000
	RS3007-3.3ASYF5	3.3	±1%	SOT23-5	SE33	Tape and Reel,3000
	RS3007-3.3AYK	3.3	±1%	SOP-8	RS3007	Tape and Reel,4000
RS3007-5.0	RS3007-5.0AYF3	5.0	±1%	SOT23-3	SE50	Tape and Reel,3000
	RS3007-5.0ASYF5	5.0	±1%	SOT23-5	SE50	Tape and Reel,3000
	RS3007-5.0AYK	5.0	±1%	SOP-8	SE50	Tape and Reel,4000

NOTE:

- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
- (2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.

7 Pin Configuration and Functions (Top View)

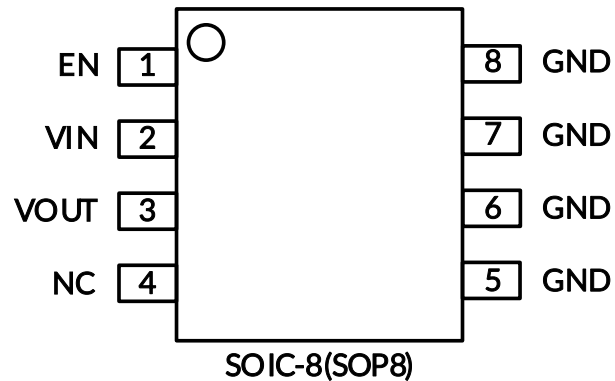


**NOTE: XX indicate Output Voltage, xx indicate Date Code
For example: SE33(V_{OUT}=3.3V)**

PIN DESCRIPTION

NAME	PIN						FUNCTION
	SOT23-3	SOT23-5	SOT89-3L (L-Type)	SOT89-3L	SOT223 (L-Type)	SOT223	
GND	1	2	1	2	1	2	Ground
VOUT	2	5	3	1	2	3	Regulator Output. Recommended output capacitor range: 1 μ F to 10 μ F.
VIN	3	1	2	3	3	1	Regulator Input. Up to 45V input voltage. At least 1 μ F supply bypass capacitor is recommended.
EN	/	3	/	/	/	/	Enable pin. Drive this pin high to enable the device, Low to put the device into low current shutdown.
NC	/	4	/	/	/	/	No internal connection

Pin Configuration and Functions (Top View)



PIN DESCRIPTION

NAME	PIN	FUNCTION
	SOIC-8(SOP8)	
EN	1	Enable pin. Drive this pin high to enable the device, Low to put the device into low current shutdown.
VIN	2	Regulator Input. Up to 45V input voltage. At least 1 μ F supply bypass capacitor is recommended.
VOUT	3	Regulator Output. Recommended output capacitor range: 1 μ F to 10 μ F.
NC	4	No internal connection
GND	5, 6, 7, 8	Ground

8 Specifications

8.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) ^{(1) (2)}

		MIN	MAX	UNIT
V _{IN}	Input voltage	-0.3	55	V
V _{EN}	V _{EN} voltage range	-0.3	V _{IN}	V
T _J	PN Junction temperature ⁽³⁾	-40	175	°C
P _D	Continuous power dissipation ⁽⁴⁾	Internally limited		W
T _{stg}	Storage temperature range	-65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltages are with respect to the GND pin.

(3) The maximum power dissipation is a function of T_{J(MAX)}, R_{θJA}, and T_A. The maximum allowable power dissipation at any ambient temperature is P_D = (T_{J(MAX)} - T_A) / R_{θJA}. All numbers apply for packages soldered directly onto a PCB.

(4) Internal thermal shutdown circuitry protects the device from permanent damage. The actual chip output current is subject to the input-output voltage difference, ambient temperature and PCB heat dissipation design.

8.2 ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

		VALUE	UNIT	
V _(ESD)	Electrostatic discharge	Human-body model (HBM)	±4000	V
		Charge device model (CDM)	±1500	V



ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

		MIN	MAX	UNIT
V _{IN}	Input supply voltage	2.5	45	V
I _{OUT}	Output current	0	300	mA
C _{IN}	Capacitor of V _{IN} pin	1	10	uF
C _{OUT}	Capacitor of V _{OUT} pin	1	10	uF
ESR	Equivalent series resistance	5	100	mΩ
T _A	Operating temperature	-40	+85 ⁽²⁾	°C

(1) All voltages are with respect to the GND pin.

(2) The chip's operating temperature is determined by the junction temperature (T_J), the relationship between T_A and T_J, please refer to the application note as below. The larger the T_A, the smaller the space left for the chip temperature rise.

8.4 Thermal Information

THERMAL METRIC		RS3007							UNIT
		SOT23-3	SOT23-5	SOT89-3L	SOT89-3L (L-Type)	SOT223 (L-Type)	SOT223	SOIC-8	
		3 PINS	5 PINS	3 PINS	3 PINS	3 PINS	3 PINS	8 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	312.5	250	75	208.3	120	84.5	110	°C/W
P _D	Power Dissipation ⁽¹⁾	0.4	0.5	1.7	0.6	1.1	1.5	1.2	W

(1) Internal thermal shutdown circuitry protects the device from permanent damage. The actual chip output current is subject to the input-output voltage difference, ambient temperature and PCB heat dissipation design.

8.5 ELECTRICAL CHARACTERISTICS

($V_{IN} = V_{OUT} + 2V$, $C_{IN} = C_{OUT} = 1\mu F$, $V_{OUT} = 3.3V$, Full = $-40^{\circ}C$ to $+85^{\circ}C$, typical values are at $T_A = +25^{\circ}C$, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS	
Input Voltage	V_{IN}		$+25^{\circ}C$	2.5 ⁽¹⁾		45	V	
Output Voltage Accuracy ⁽²⁾		$I_{OUT} = 10mA$	$+25^{\circ}C$	-2.0		2.0	%	
		$I_{OUT} = 10mA$, A Type	$+25^{\circ}C$	-1.0		1.0	%	
Ground Pin Current	I_Q	No load	$+25^{\circ}C$		3.0	4.0	μA	
Shutdown Current	I_{Q-OFF}	$V_{EN} = 0V$	$+25^{\circ}C$		0.1	1.0	μA	
Max Output Current ⁽³⁾			$+25^{\circ}C$	300	350	-	mA	
Dropout Voltage ⁽⁴⁾	$V_{DROPOUT}$ $I_{OUT} = 100mA$	$V_{OUT} = 1.8V$	$+25^{\circ}C$	-	450	550	mV	
		$V_{OUT} = 2.5V$		-	385	485		
		$V_{OUT} = 3.0V$		-	350	450		
		$V_{OUT} = 3.3V$		-	335	435		
		$V_{OUT} = 5.0V$		-	300	400		
Line Regulation	$\frac{\Delta V_{OUT}}{\Delta V_{IN} \times V_{OUT}}$	$V_{IN} = V_{OUT} + 2V$ to $36V$, $I_{OUT} = 1mA$	$+25^{\circ}C$	-	0.05	0.2	%/V	
Load Regulation	ΔV_{OUT}	$V_{IN} = V_{OUT} + 1V$, $I_{OUT} = 1mA$ to $50mA$	$+25^{\circ}C$	-	5	20	mV	
Output Current Limit	I_{LMT}	$V_{IN} = V_{OUT} + 1V$	$+25^{\circ}C$	300	450	-	mA	
Short-Circuit Current	I_{short}	$V_{OUT} = 0$	$+25^{\circ}C$	-	100	-	mA	
Power Supply Rejection Ratio	PSRR	$V_{OUT} = 3.3V$, $I_{OUT} = 10mA$	$f = 217Hz$	$+25^{\circ}C$	-	72	-	dB
			$f = 1KHz$		-	77	-	
			$f = 10KHz$		-	60	-	
EN Input Threshold	V_{ENH}		$+25^{\circ}C$	1.2	-	-	V	
	V_{ENL}			-	-	0.4	V	
Output Voltage Temperature Coefficient ⁽⁵⁾	$\frac{\Delta V_{OUT}}{\Delta T_A \times V_{OUT}}$	$I_{OUT} = 1mA$	FULL	-	100	-	ppm/ $^{\circ}C$	
Output Noise Voltage	e_n	$V_{IN} = V_{OUT} + 1V$, $I_{OUT} = 1mA$, $V_{OUT} = 3.0V$ $f = 10Hz$ to $100KHz$		-	100	-	μV_{rms}	
Thermal Shutdown Temperature	T_{SHDN}			-	170	-	$^{\circ}C$	
Thermal Shutdown Hysteresis Temperature	T_{SDH}			-	20	-	$^{\circ}C$	

NOTES:

- $V_{IN} \geq V_{OUT(NOMINAL)}$, whichever is greater.
- Option $\pm 1\%$ output voltage accuracy.
- Maximum output current is affected by the PCB layout, size of metal trace, the thermal conduction path between metal layers, ambient temperature and the other environment factors of system. Attention should be paid to the dropout voltage when $V_{IN} < V_{OUT} + V_{DROPOUT}$.
- The dropout voltage is defined as $V_{IN} - V_{OUT}$, when V_{OUT} is 100mV below the value of V_{OUT} for $V_{IN} = V_{OUT(NOMINAL)} + 2V$.
- Output voltage temperature coefficient is defined as the worst-case voltage change divided by the total temperature range.

8.6 TYPICAL CHARACTERISTICS

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

($V_{IN} = V_{OUT} + 2V$, $C_{IN} = C_{OUT} = 1\mu F$, $V_{OUT} = 3.3V$, Full = $-40^{\circ}C$ to $+85^{\circ}C$, typical values are at $T_A = +25^{\circ}C$, unless otherwise noted.)

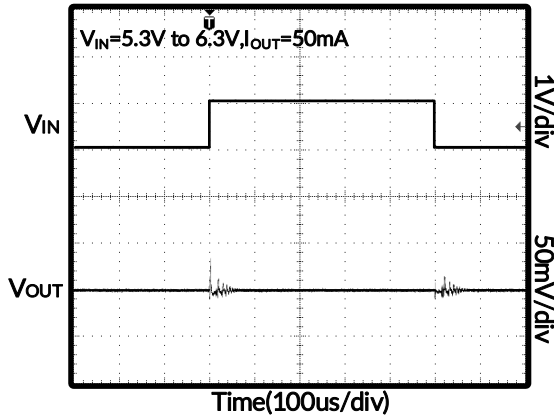


Figure 1. Line Transient Response

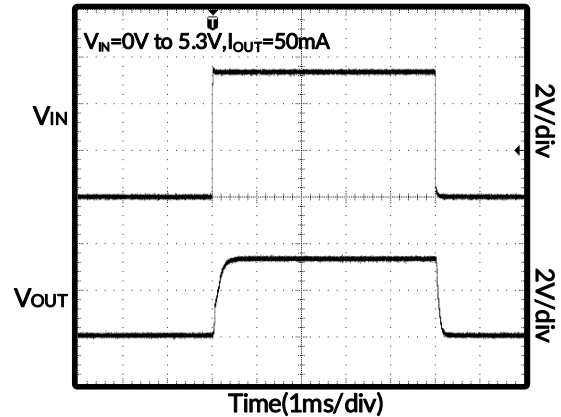


Figure 2. Power-Up/Power-Down Output Waveform

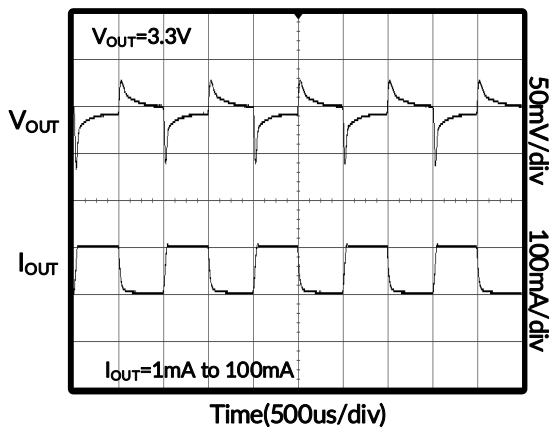


Figure 3. Load Transient Response

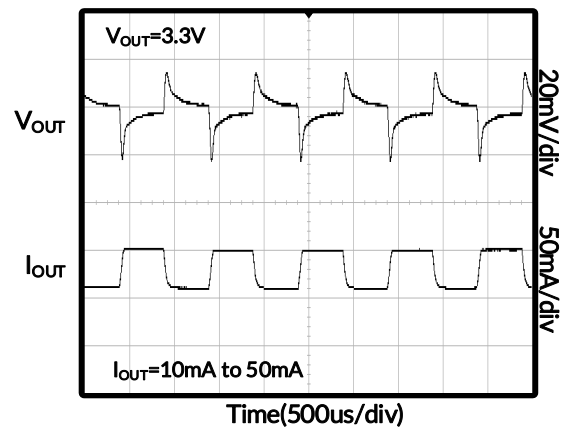


Figure 4. Load Transient Response

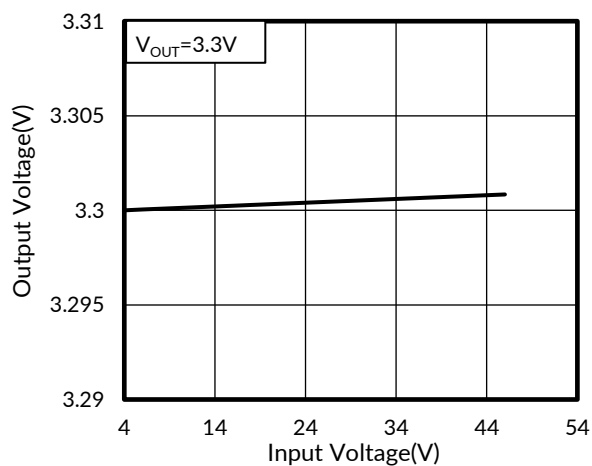


Figure 5. Line Regulation

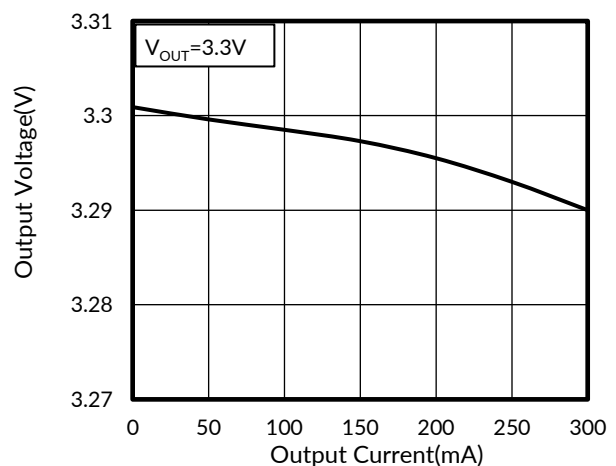


Figure 6. Load Regulation

TYPICAL CHARACTERISTICS

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

($V_{IN} = V_{OUT} + 2V$, $C_{IN} = C_{OUT} = 1\mu F$, $V_{OUT} = 3.3V$, Full = $-40^{\circ}C$ to $+85^{\circ}C$, typical values are at $T_A = +25^{\circ}C$, unless otherwise noted.)

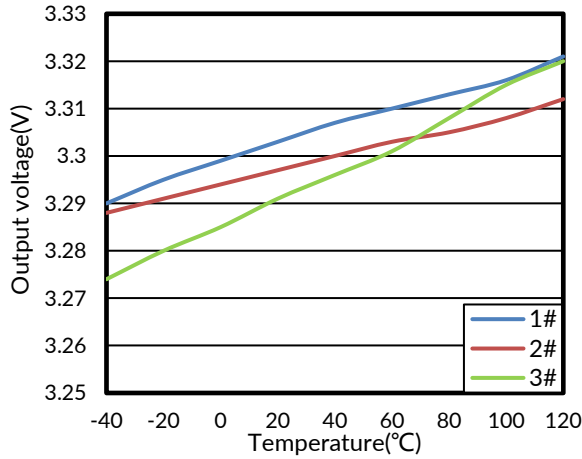


Figure 7. V_{OUT} vs Temperature

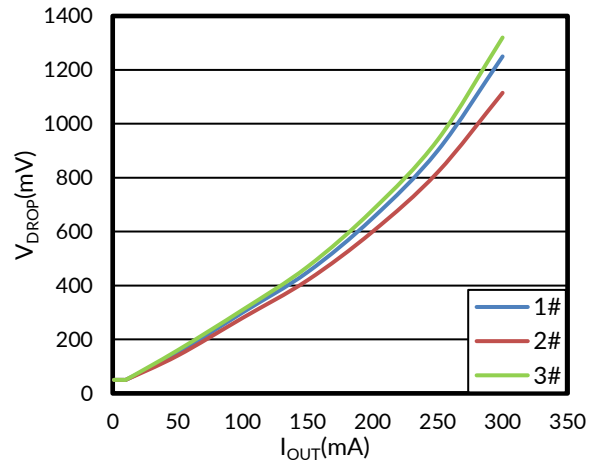


Figure 8. V_{DROP} vs I_{OUT}

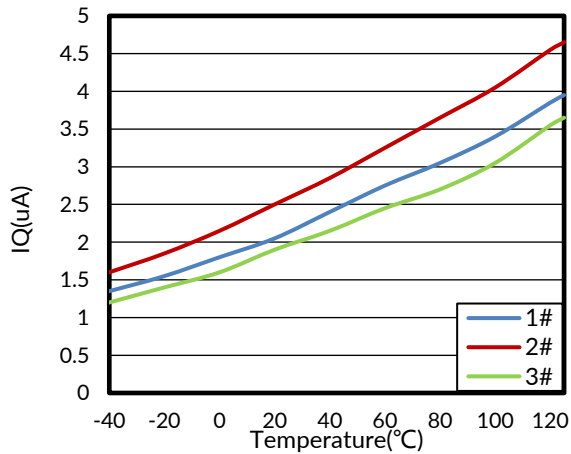


Figure 9. I_Q vs Temperature

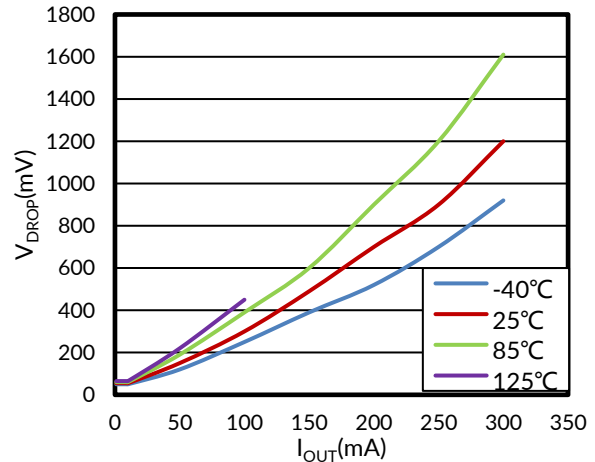


Figure 10. $V_{DROP} - I_{OUT}$ vs Temperature

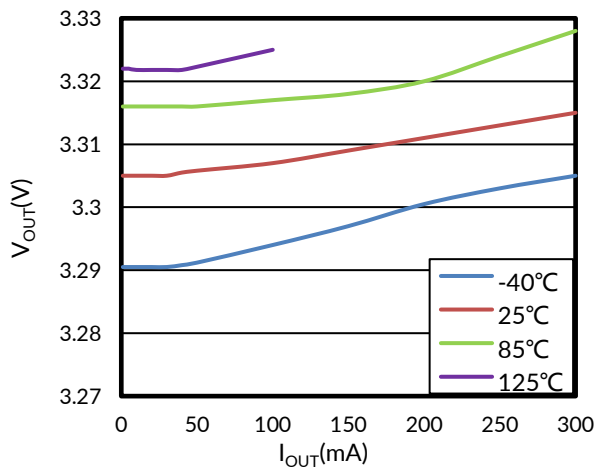


Figure 11. $V_{OUT} - I_{OUT}$ vs Temperature

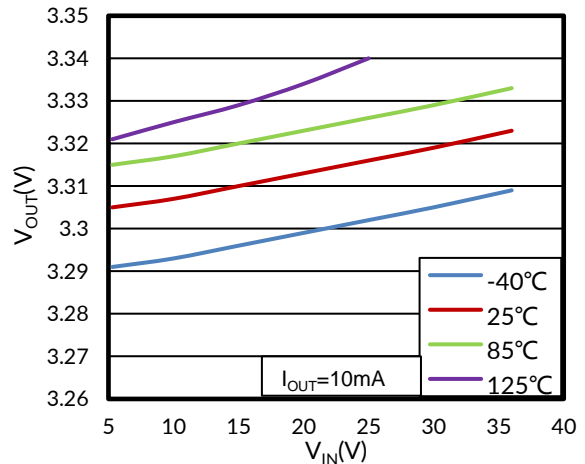


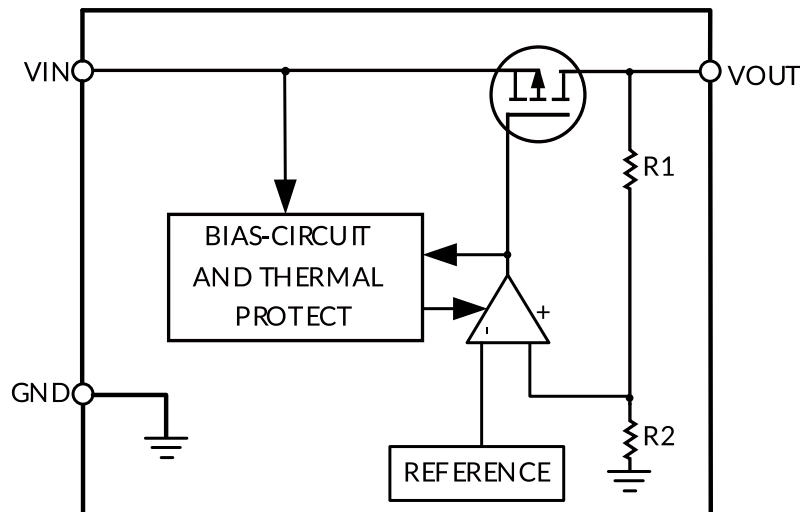
Figure 12. $V_{OUT} - V_{IN}$ vs Temperature

9 DETAILED DESCRIPTION

9.1 Overview

The RS3007 low-dropout regulators (LDO) consumes only 3 μ A of quiescent current at light load and delivers excellent line and load transient performance. These characteristics, combined with low noise and good PSRR with low dropout voltage, make this device ideal for portable consumer applications.

9.2 Functional Block Diagram



9.3 Thermal Considerations

When the junction temperature is too high, the thermal protection circuitry sends a signal to the control logic that will shut down the IC. The IC will restart when the temperature has sufficiently cooled down. The maximum power dissipation is dependent on the thermal resistance of the case and the circuit board, the temperature difference between the die junction and the ambient air, and the rate of air flow. The GND pin must be connected to the ground plane for proper dissipation.

9.4 Applications Note:

- 1) The phase compensation circuit and ESR of the output capacitor are used inside the circuit to compensate, so a capacitor larger than 1.0 μ F must be connected to the ground.
- 2) It is recommended to use 1 μ F polar capacitors for input and output, and to keep the capacitors as close to the V_{IN} and V_{OUT} pins of LDO as possible.
- 3) Pay attention to the use conditions of input and output voltages and load currents to avoid the power consumption (PD) inside the IC exceeding the maximum power consumption allowed by the package.

$$PD = (V_{IN} - V_{OUT}) \times I_{OUT}$$

$$T_{PN} = PD \times R_{\theta JA} + T$$

T_{PN} is junction temperature

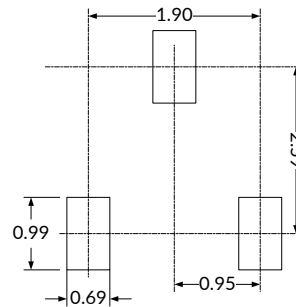
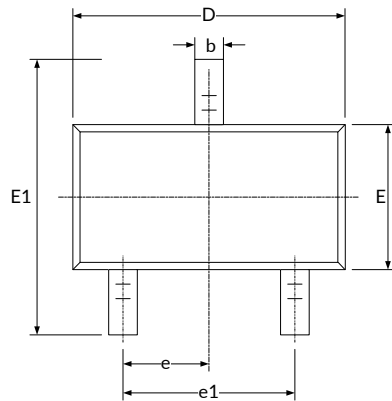
T is ambient temperature.

- 4) When the input voltage V_{IN} is greater than 2.5V, if V_{IN} is also higher than the output set value plus the device dropout voltage, V_{OUT} is equal to the set value. Otherwise, V_{OUT} is equal to V_{IN} minus the dropout voltage. If V_{IN} lower than 2.5V, the V_{OUT} is:

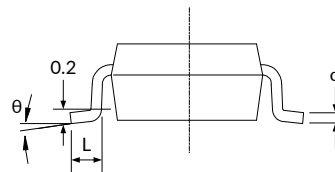
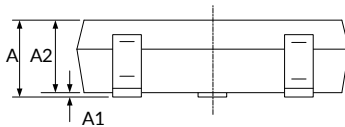
$$V_{OUT} = V_{IN} - V_{Dropout}$$

10 PACKAGE OUTLINE DIMENSIONS

SOT23-3⁽³⁾



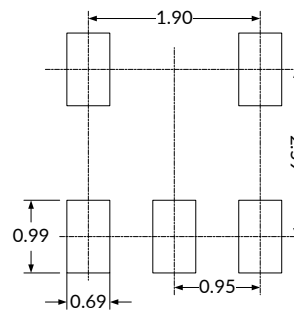
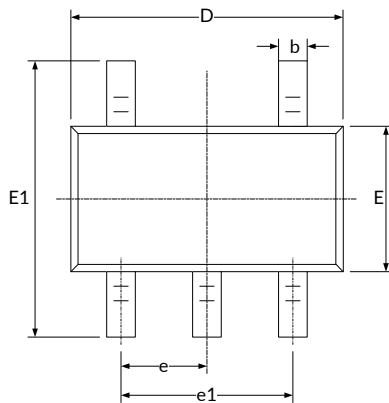
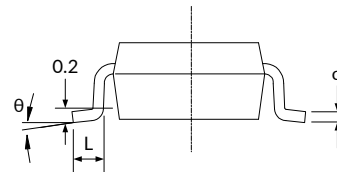
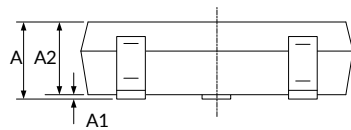
RECOMMENDED LAND PATTERN (Unit: mm)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D ⁽¹⁾	2.820	3.020	0.111	0.119
E ⁽¹⁾	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC) ⁽²⁾		0.037(BSC) ⁽²⁾	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

NOTE:

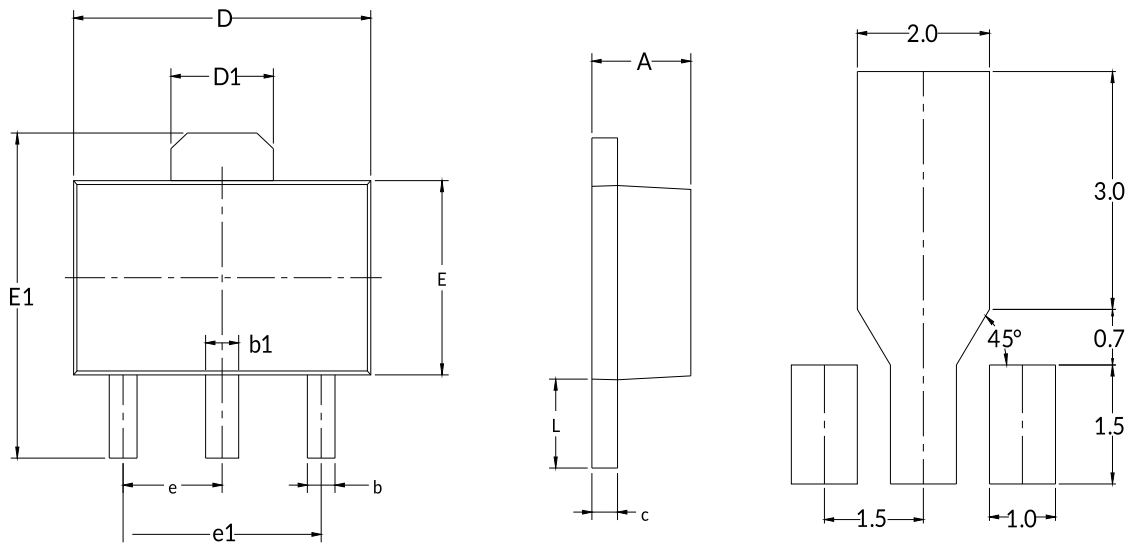
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

SOT23-5⁽³⁾

RECOMMENDED LAND PATTERN (Unit: mm)


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D ⁽¹⁾	2.820	3.020	0.111	0.119
E ⁽¹⁾	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC) ⁽²⁾		0.037(BSC) ⁽²⁾	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

NOTE:

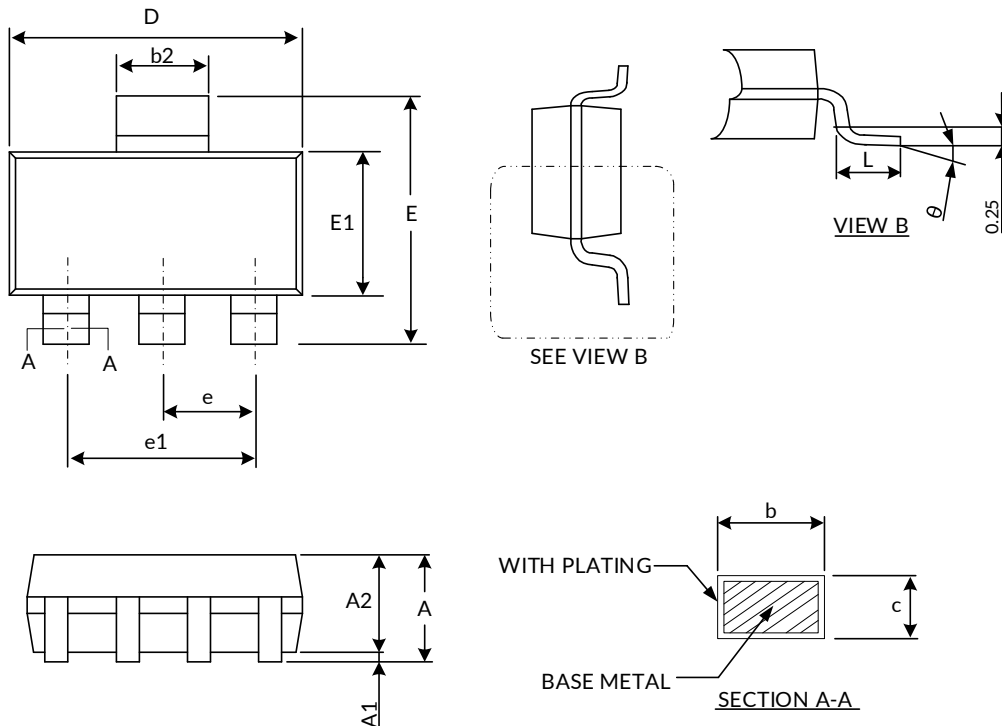
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

SOT89-3L (4)

RECOMMENDED LAND PATTERN (Unit: mm)

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.400	0.580	0.016	0.023
c	0.350	0.440	0.014	0.017
D ⁽¹⁾	4.400	4.600	0.173	0.181
D1	1.550 REF ⁽²⁾		0.061 REF ⁽²⁾	
E ⁽¹⁾	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
e	1.500 BSC ⁽³⁾		0.060 BSC ⁽³⁾	
e1	3.000 BSC ⁽³⁾		0.118 BSC ⁽³⁾	
L	0.900	1.200	0.035	0.047

NOTE:

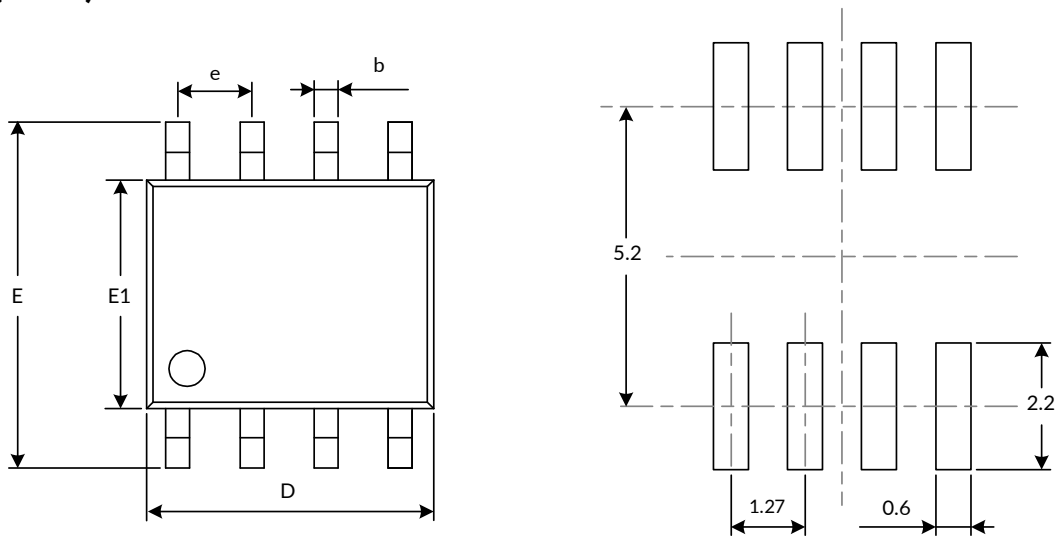
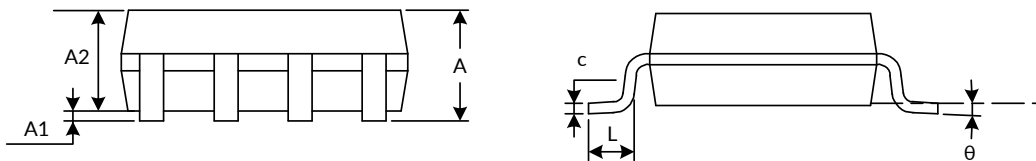
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. REF is the abbreviation for Reference.
3. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
4. This drawing is subject to change without notice.

SOT223⁽³⁾


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	-	1.800	-	0.071
A1	0.02	0.10	0.001	0.004
A2	1.55	1.65	0.061	0.065
b	0.66	0.84	0.026	0.033
b2	2.90	3.10	0.114	0.122
c	0.23	0.33	0.009	0.013
D ⁽¹⁾	6.30	6.70	0.248	0.263
E	6.70	7.30	0.263	0.287
E1 ⁽¹⁾	3.30	3.70	0.130	0.145
e	2.30 BSC ⁽²⁾		0.090 BSC ⁽²⁾	
e1	4.60 BSC ⁽²⁾		0.181 BSC ⁽²⁾	
L	0.90	-	0.035	-

NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

SOIC-8(SOP8) (3)

RECOMMENDED LAND PATTERN (Unit: mm)


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D ⁽¹⁾	4.800	5.000	0.189	0.197
e	1.270(BSC) ⁽²⁾		0.050(BSC) ⁽²⁾	
E	5.800	6.200	0.228	0.244
E1 ⁽¹⁾	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

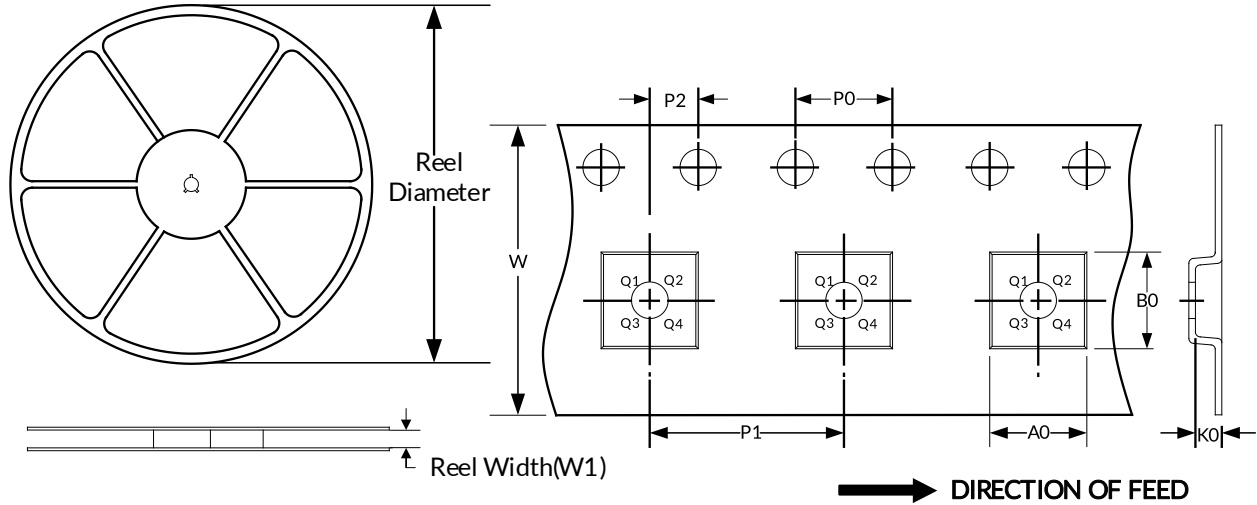
NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

11 TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSION



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width(mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOT23-3	7"	9.0	3.20	3.30	1.30	4.0	4.0	2.0	8.0	Q3
SOT23-5	7"	9.5	3.20	3.20	1.40	4.0	4.0	2.0	8.0	Q3
SOT89-3L	7"	13.2	4.85	4.45	1.85	4.0	8.0	2.0	12.0	Q3
SOT223	13"	12.4	6.765	7.335	1.88	4.0	8.0	2.0	12.0	Q3
SOIC-8(SOP8)	13"	12.4	6.40	5.40	2.10	4.0	8.0	2.0	12.0	Q1

NOTE:

1. All dimensions are nominal.
2. Plastic or metal protrusions of 0.15mm maximum per side are not included.

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